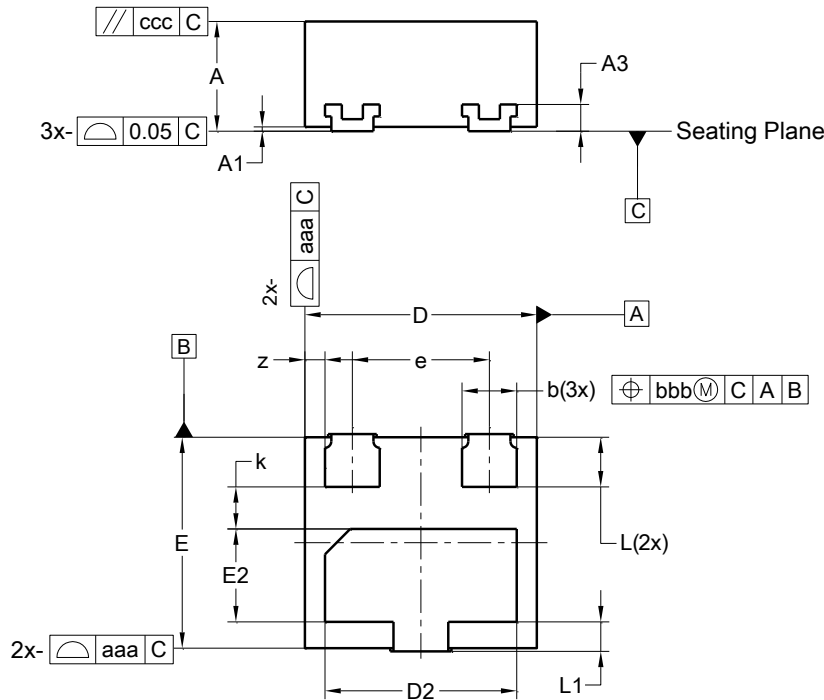


Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN1110-3/SWP (Type A)



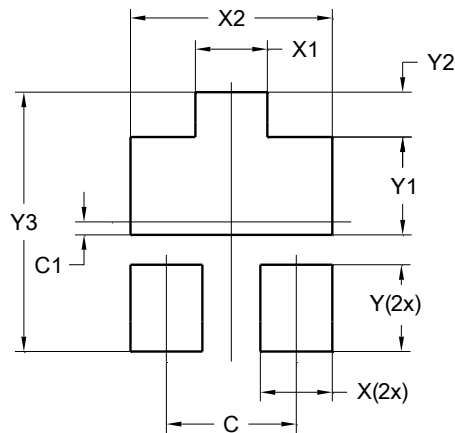
U-DFN1110-3/SWP (Type A)			
Dim	Min	Max	Typ
A	0.47	0.57	0.52
A1	0.00	0.05	0.03
A3	-	-	0.127
b	0.22	0.30	0.26
D	1.05	1.15	1.10
D2	0.87	0.95	0.91
e	0.65 BSC		
E	0.95	1.05	1.00
E2	0.40	0.48	0.44
k	-	-	0.20
L	0.20	0.27	0.23
L1	0.09	0.19	0.14
z	-	-	0.095
aaa	0.25		
bbb	0.10		
ccc	0.10		
All Dimensions in mm			

Note: Side wall tin plated package for wettable flanks in AOI.

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN1110-3/SWP (Type A)



Dimensions	Value (in mm)
C	0.650
C1	0.065
X	0.360
X1	0.360
X2	1.010
Y	0.435
Y1	0.490
Y2	0.225
Y3	1.300

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.